

RICH Upgrade Status / 09 October 2007

- Last minute changes on the frame drawings (delayed production 2-3 weeks):
 - ▶ gas Inlet/Outlet moved in better (protected) position
 - ▶ wire stretching procedure improved (direct soldering on PCB)
 - ▶ sense wire boards layout optimized for assembling
 - ▶ fixed mismatching between HV wire PCB frame thickness (1.6 or 2 mm available for our 682 mm long non standard boards) and Mechanical Engineer assumption (1.8 mm for standard PCB)
 - ▶ frames delivery: end of October (was 10/October/07)
- New pad plane holder (for storage and transportation of 5 pad planes from SBU to JLab) designed and ordered (formal offer pending)

We expect to be 2-3 weeks late.

As mentioned many times: RICH installation should occur a couple of months (max) before running the experiment (in order to minimize evaporated CsI degradation)